Notification Number: 20220	FOC	0000.0 Notification	Dat		May 10, 2022
, , ,					
	<u>er</u>		L	Je	pt: Quality Services
Change Type:		.		_	W C B C:
Assembly Site		Design	- 	4	Wafer Bump Site
Assembly Process	M	Data Sheet	┵	4	Wafer Bump Material
Assembly Materials		Part number change	┵	4	Wafer Bump Process
Mechanical Specification		Test Site		┽	Wafer Fab Site
Packing/Shipping/Labeling		Test Process	+ +	+	Wafer Fab Materials
	NI.	atification Details			Wafer Fab Process
Description of Change:	N	otification Details			
Texas Instruments Incorporated is The product datasheet(s) is being the following change history provides Texas	upd	ated as summarized belov		nc	
INSTRUMENTS		Sc	LS147	G-	SN54HC573A, SN74HC573A - DECEMBER 1982 – REVISED APRIL 2022
Changes from Revision E (Septembe	r 20	03) to Revision F (October 2	016)		Page
 Deleted Ordering Information table; Changed Package thermal impedant 49.1 (N), and from 83 to 101.1 (PW). TEXAS INSTRUMENTS	ce, F	R _{θJA} , values from 70 to 92.5 (D	0B), fi	ror	m 58 to 78.3 (DW), from 69 to
Changes from Revision E (December	202	1) to Revision F (April 2022)			Page
Junction-to-ambient thermal resistan N was 69 is now 84.6, NS was 60 is					
TEXAS INSTRUMENTS		s	CLS13	6F -	SN54HC273, SN74HC273 - DECEMBER 1982 - REVISED APRIL 2022
Changes from Revision E (August 20	03) 1	to Revision F (April 2022)			Page
 Updated the ESD ratings table to fit r Changed Package thermal impedant 45.1(N), from 60 to 72.6 (NS), and free Updated Power Supply Recommend 	ce, F om 8	R _{θJA} , values from 70 to 90.3 (Di 33 to 98.3 (PW)	3), fro	om	1 58 to 77.4(DW), from 69 to
TEXAS INSTRUMENTS Changes from Revision F (December Junction-to-ambient thermal resistant	ce v	1) to Revision G (April 2022) alues increased. DW was 58 is	s now	/ 1	The state of the s
N was 69 is now 84.6, NS was 60 is	now	113.4, PW was 83 is now 131	.8		4

SCLS140F - DECEMBER 1982 - REVISED APRIL 2022

Changes from Revision E (January 2022) to Revision F (April 2022)

Page

Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7.

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74HC573A, SN54HC573A	SCLS147F	SCLS147G
SN54HC240, SN74HC240	SCLS128F	SCLS128G
SN54HC273, SN74HC273	SCLS136E	SCLS136F
SN74HC374, SN54HC374	SCLS141F	SCLS141G
SN54HC373	SCLS140E	SCLS140F

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/SN74HC573A

http://www.ti.com/product/SN54HC240

http://www.ti.com/product/SN54HC273

http://www.ti.com/product/SN74HC374

http://www.ti.com/product/SN54HC373

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

SN74HC240DBR	SN74HC240PWRG4	SN74HC273PWR	SN74HC374NSR
SN74HC240DW	SN74HC240PWT	SN74HC273PWRG4	SN74HC374PWR
SN74HC240DWE4	SN74HC273DBR	SN74HC273PWT	SN74HC374PWT
SN74HC240DWG4	SN74HC273DW	SN74HC374DBR	SN74HC573ADBR
SN74HC240DWR	SN74HC273DWR	SN74HC374DW	SN74HC573ADW
SN74HC240N	SN74HC273DWRE4	SN74HC374DWE4	SN74HC573ADWR
SN74HC240NE4	SN74HC273DWRG4	SN74HC374DWG4	SN74HC573ADWRG4
SN74HC240NS	SN74HC273N	SN74HC374DWR	SN74HC573AN
SN74HC240NSR	SN74HC273NE4	SN74HC374DWRG4	SN74HC573ANE4
SN74HC240NSRE4	SN74HC273NS	SN74HC374N	SN74HC573APWR
SN74HC240PW	SN74HC273NSR	SN74HC374NE4	SN74HC573APWRG4
SN74HC240PWR	SN74HC273PW	SN74HC374NS	SN74HC573APWT

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Location	E-Mail
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